

**In The Specification:**

At page 14, after line 11, please insert the following paragraph:

As shown in Figures 2a-b, the substrate **10** may have opposing first and second surfaces (e.g. the device side **20** and backside **120**). The solder bumps **40** may provide a first array of interconnection structures on the device side **20** of the substrate **10**, and the first array of interconnection structures may be arranged in a first pattern. The contact pads **140** may provide a second array of interconnection structures on the backside **120** of the substrate **10**, and the second array of interconnection structures may be arranged in a second pattern and that is a mirror image of the first pattern. The solder bumps **50** may provide a third array of interconnection structures on the device side **20** of the substrate **10** spaced apart from the first array of interconnection structures, and the third array of interconnection structures may be arranged in a third pattern. The contact pads **150** may provide a fourth array of interconnection structures on the backside **120** of the substrate **10** spaced apart from the second array of interconnection structures, and the fourth array of interconnection structures may be arranged in a fourth pattern that is a mirror image of the third pattern.